

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.43	100.0	8.2
			Subtotal	0.43	100	8.2
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.36	100.0	6.8
			Subtotal	0.36	100	6.8
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.37	100.0	26
			Subtotal	1.37	100	26
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03	0.04	0.52
	Copper alloy	Iron (Fe)	7439-89-6	0.07	0.1	1.29
	Copper alloy	Copper (Cu)	7440-50-8	67.79	99.86	1287.2
			Subtotal	67.89	100	1289.01
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.58	8.7	48.94
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.74	16.0	90
	Filler	Silica fused	60676-86-0	22.22	75.0	421.88
	Carbon Black	Carbon black	1333-86-4	0.09	0.3	1.69
			Subtotal	29.63	100	562.51
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.02	5.0	0.31
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.16
	Lead alloy	Lead (Pb)	7439-92-1	0.31	92.5	5.81
			Subtotal	0.34	100	6.28
			Total	100.02	100	1898.8

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